SUBSTITUTE SPECIFICATION
CLEAN COPY

INK JET RECORDING HEAD AND METHOD FOR MANUFACTURING INK JET RECORDING HEAD

BACKGROUND OF THE INVENTION

Field of the Invention

The present invention relates to an ink jet recording head, and a method for manufacturing an ink jet recording head.

Related Background Art

A liquid discharge recording apparatus is a recording apparatus of the so-called non-impact recording type which can perform recording at high speed and use various kinds of recording mediums for recording. Then, it is characterized in that almost no noise is generated at the time of recording. For the liquid discharge recording methods adoptable for a liquid discharge recording apparatus of this kind, there is, as the typical example thereof, a method that uses an electrothermal converting device as a discharge energy generating element. The liquid discharge recording head that uses this method provides an electrothermal converting device in each pressure chamber, and provides thermal energy for recording liquid when the electric pulses, which serve as

recording signals, are applied to electrothermal converting devices. This generates a change of state of the recording liquid, and then, the bubbling pressure of the recording liquid exerted at the time of bubbling (at the time of boiling) is utilized for discharging recording liquid droplets.

Further, of the liquid discharge recording heads that use the electrothermal converting method, there are the one that adopts the method in which recording liquid is discharged in parallel to the base plate having the electrothermal converting devices arranged therefor (edge shooter) and the one that adopts the method in which recording liquid is discharged perpendicularly to the base plate having the electro-thermal converting devices arranged therefor (side shooter).

Fig. 17 is a view which shows the state where the recording element base plate, which constitutes the background art of the application hereof, is mounted on a supporting member.

As shown in Fig. 17, a plurality of discharge ports 104a for discharging recording liquid are arranged on the discharge port plate 104 provided for the recording element base plate 103 on a surface thereof to be open in two lines in a position facing the discharge energy generating elements (electrothermal converting devices, for example) 105, and the discharge port array is structured to form a

pair of lines. The recording liquid supply path 101a has a flow path width larger than the opening width of the inlet portion of the recording liquid supply port 106. As a result, the thickness of a partition wall 101b that partitions two recording supply paths 101a adjacent to each other is smaller than the pitch between the inlet portions themselves of two recording liquid supply ports 106 adjacent to each other.

There have been known several assembling methods or the like used for the manufacture of such recording element base plate as described above and the liquid discharge head that includes such base plate.

For example, in the specification of Japanese Patent Laid-Open Application No. 09-187952, an assembling method is disclosed to position the recording element base plate with respect to a method for manufacturing a liquid discharge head. This assembling method is such as to position the recording element base plate in good precision by use of vacuum adsorption fingers, and then, to fix the recording element base plate by the application of a bonding agent of the type that dually uses ultraviolet and thermal hardening.

Also, in the specification of Japanese Patent Laid-Open Application No. 11-179923, a method is disclosed for bonding an orifice plate (discharge port plate) to the main body of a liquid discharge head.

Also, in the specification of Japanese Patent Laid-Open Application No. 11-188873, a method is disclosed for bonding a nozzle member to the main body of a liquid discharge head which is provided with a plurality of ink chambers.

Of the recording element base plates described above, the second recording element base plate 103, which is provided with a plurality of discharge port arrays, in particular, makes it necessary to narrow the pitch between adjacent recording liquid supply ports 106 in a case where the number of recording element base plates is increased to implement a cost reduction when the base plates are cut out from one silicon wafer or where the number of discharge port arrays is increased without making the recording element base plate larger.

If the pitch between recording liquid supply ports 106 is made smaller, there is a need for making the thickness of the partition wall 101b of the supporting member 101 smaller accordingly. However, if the partition wall 101b is made thinner, there are problems that may be encountered as noted below.

(1) It is difficult to form the ceramic supporting member 101 with thin partition walls less than a certain thickness, from the viewpoint of manufacture.

(2) If the partition walls 101b are thin, vibration waves are propagated to adjacent supply flow paths through the partition walls 101b when recording

liquid is discharged. Then, in the adjacent supply flow paths, the supply of the recording liquid becomes defective due to the propagated vibrations, resulting in defective printing.

(3) Further, if the partition walls 101b are thin, it becomes necessary to make the assembling precision higher for the recording element base plate 103 in relation to the supporting member 101 so as not to allow the adjacent supply flow paths 101a themselves to mix recording liquids.

On the other hand, if the partition walls 101b are made too thick, the width of the supply flow paths 101a becomes narrower, making it impossible to supply recording liquid to the recording liquid supply ports 106 in a sufficient amount.

Therefore, if the pitch between the recording supply ports themselves is to be made smaller, it is necessary to determine the thickness of the partition walls 101b to be formed in the supporting base plate 101 and the width of the supply flow paths 101a in consideration of those aspects described above.

Also, for the assembling method or the like described above, which is used for the manufacture of the recording element base plate and the manufacture of the liquid discharge head that includes that of the recording element base plate, the following drawback is encountered:

(1) Regarding the locations having coated thereon the dual type bonding agent of ultraviolet and thermal hardening, the irradiated ultraviolet rays do not reach the locations in the shadow of the adsorption fingers that adsorb the recording element base plate. As a result, the recording element base plate is transferred to the next hardening process while the positioning fixation has not been completed, and the positioning of the recording element base plate is deviated eventually.

(2) The viscosity of the dual type bonding agent of ultraviolet and thermal hardening on the locations where irradiated ultraviolet rays do not reach as described above is made extremely low immediately before hardening in the thermal harding step, and then, due to capillary force, the bonding agent is transferred to the corner portions inside the recording liquid flow path. As a result, the discharge nozzles become clogged.

SUMMARY OF THE INVENTION

It is an object of the present invention to optimize the discharge characteristics of the recording liquid and the supply characteristics thereof, as well as the positioning precision of a recording element base plate to a supporting member.

(For the following paragraph, the reader is referred to Figs. 15 and 16A).

In order to achieve the object described above, the ink jet recording head has a plurality of discharge energy generating devices 4 for discharging recording liquid, while being provided with a recording element base plate 1 arranged on the face opposite to the surface where the devices 4 are arranged, having a plurality of recording liquid supply ports 5 for supplying recording liquid to the devices 4, as well as with a supporting member 2 that holds and fixes the recording element base plate 1. For the supporting member 2, a plurality of recording liquid supply flow paths 2a are arranged to supply recording liquid to each of the supply ports 5 of the recording element base plate 1, respectively, and then, the flow path width of each supply flow path 2a is formed to be smaller than the opening width of the inlet portion of each supply port 5. Further, the step created between the supply flow path 2a and the supply port 5 is buried by the bonding agent 10 forced out from the bonding face of the recording element base plate 1 and the supporting member 2.

BRIEF DESCRIPTION OF THE DRAWINGS

Fig. 1 is a perspective view which shows the assembled state of a recording head and ink tanks for a recording head cartridge in accordance with one embodiment of the present invention.

Fig. 2 is a view which shows the unassembled state of the recording head and the ink tanks for the recording head cartridge in accordance with one embodiment of the present invention.

Fig. 3 is an exploded perspective view which shows the recording head cartridge represented in Fig. 1.

Fig. 4 is an exploded perspective view which shows the ink supply unit and the recording element unit represented in Fig. 3.

Fig. 5 is a partly broken perspective view which shows a part of the first recording element base plate represented in Fig. 4.

Fig. 6 is a partly broken perspective view which shows a part of the second recording element base plate represented in Fig. 4.

Fig. 7 is a cross-sectional view which shows the recording head cartridge represented in Fig. 1.

Fig. 8 is a perspective view which shows a device for coupling the recording element unit and the ink supply unit of the recording head cartridge represented in Fig. 1.

Fig. 9 is a perspective view which shows the bottom end of the recording head cartridge represented in Fig. 1.

Figs. 10A, 10B and 10C are cross-sectional views which illustrate a method for manufacturing an ink jet recording head in accordance with one embodiment of the present invention.

Figs. 11A and 11B are cross-sectional views which illustrate the method for manufacturing an ink jet recording head in accordance with one embodiment of the present invention.

Figs. 12A and 12B are cross-sectional views which illustrate the method for manufacturing an ink jet recording head in accordance with one embodiment of the present invention.

Fig. 13 is a perspective view which shows a first recording element base plate represented in Fig. 11B in the assembling step.

Fig. 14 is a perspective view which shows a second recording element base plate represented in Fig. 11B in the assembling step.

Fig. 15 is a cross-sectional view which shows the state in which the recording device included in an ink jet recording head is mounted on a supporting member in accordance with a second embodiment of the present invention.

Figs. 16A and 16B are cross-sectional views which illustrate the bonding step for the recording element base plate and the supporting member represented in Fig. 15.

Fig. 17 is a view which shows the state in which the recording element base plate is mounted on the supporting member, which is the related background art of the application hereof.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

Now, with reference to the accompanying drawings, the description will be made of the embodiments in accordance with the present invention.

(First Embodiment)

Fig. 1 to Fig. 6 are views which illustrate the head cartridge, the recording head, and the ink tanks, respectively, embodying the present invention or to which the present invention is applicable, and the relationships between them as well. Hereunder, with reference to Fig. 1 to Fig. 6, each of the constituents will be described.

As understandable from Fig. 1 and Fig. 2, the recording head H1001 of the present invention is one constituent that forms a recording head cartridge H1000. The recording head cartridge H1000 comprises the recording head H1001, and the ink tanks H1900 (H1901, H1902, H1903, and H1904) which are detachably mountable on the recording head H1001. The recording head cartridge H1000 is supported to be fixed on the main body of an ink jet recording apparatus by positioning means and electrical contacts of a carriage (not shown), while being detachably mountable on the carriage. The ink tank H1901 is for black ink use, the ink tank H1902 for cyan ink use, the ink tank H1903 for magenta ink use, and the ink tank H1904 for yellow ink use. In this manner, the ink tanks H1901, H1902, H1903, and H1904 are detachably mountable on the

recording head H1001, respectively, and each of the tanks is made replaceable to reduce the running costs of image recording by the ink jet recording apparatus.

Next, the detailed description will be made of the recording head H1001 per constituent that forms the recording head one after another.

<1> Recording head

The recording head H1001 is one which is called a side shooter type using the bubble jet type that records using electrothermal converting devices to generate thermal energy for creating film boiling in ink in accordance with electric signals.

As shown in Fig. 3 which is an exploded perspective view, the recording head H1001 comprises a recording element unit H1002; an ink supply unit H1003; and a tank holder H2000.

Further, as shown in Fig. 4 which is also an exploded perspective view, the recording element unit H1002 comprises a first recording element base plate H1100; a second recording element base plate 1101; a first plate H1200; an electric wiring tape H1300; an electric contact board H2200; and a second plate H1400. Also, the ink supply unit H1003 comprises an ink supply member H1500; a flow path formation member H1600; a joint rubber H2300; a filter H1700; and a sealing rubber H1800.

<1 - 1> Recording element unit

Fig. 5 is a partly exploded perspective view which shows the first recording element base plate H1100.

For the first recording element base plate H1100, the ink supply port H1102 is formed by an elongated through opening as an ink flow path on the Si base plate H1110 of 0.5 mm to 1.0 mm thickness, for example, by means of anisotropic etching utilizing the Si crystal orientation, sand blasting, or the like. Then, on both sides across the ink supply port H1102, the electrothermal converting devices H1103, which serve as recording elements, are arranged in zigzag fashion forming two lines. The electrothermal converting devices H1103 and the electric wiring of Al or the like that supply electric power to each of the electrothermal converting devices H1103 are formed by means of a film formation technique. Further, an electrode unit H1104 that supplies electric power to the electric wiring is arranged on each outer side of the lines of electrothermal converting devices H1103, and bumps H1105 of Au or the like are formed for the electrode units H1104, respectively. Then, on the Si base plate, the ink flow path walls H1106 and the discharge ports H1107 are formed with resin material by means of a photolithographic technique for the formation of ink flow paths corresponding to the electrothermal converting devices H1103, hence forming the discharge port array H1108. Therefore, ink supplied from the ink supply port H1102 is discharged

by means of bubbles which are generated by each electrothermal converting device H1103, because each discharge port H1107 is arranged to face a corresponding electrothermal converting device H1103.

Also, Fig. 6 is a partly broken perspective view which shows the second recording element base plate H1101.

The second recording element base plate H1101 is one for discharging inks of three colors. Three ink supply ports H1102 are formed in parallel, and electrothermal converting devices and ink discharge ports are formed on both sides of each of the ink supply ports . In the same manner as forming the first recording element base plate H1100, the ink supply ports, electrothermal converting devices, electric wiring, electrodes, and other elements are formed on the Si base plate, of course, and the ink flow paths and ink discharge ports are formed thereon with a resin material by use of a photolithographic technique.

Then, as in the case of the first recording element base plate, the electrode units H1104 and the bumps H1105 of Au or the like are formed to supply electric power to the electric wiring.

Here, reverting to Fig. 4, the first plate H1200 is formed by Alumina (Al_2O_3) material of 0.5 to 10 mm thickness, for example. In this respect, the material of the first plate is not necessarily limited to alumina, but it may be possible to produce this plate

with a material which has the same linear expansion coefficient as that of the material of the recording element base plate H1100, and also, has the same heat conductivity or more than that of the material of the recording element base plate H1100. The material of the first plate H1200 may be any one of silicon (Si), aluminum nitride (AlN), zirconium, silicon nitride (Si_3N_4), silicon carbide (SiC), molybdenum (Mo), and tungsten (W), for example. For the first plate H1200, there are formed the ink supply port H1201 for supplying black ink to the first recording element base plate H1100, and the ink supply ports H1201 for supplying cyan, magenta, and yellow ink to the second recording element base plate H1101. Then, the ink supply ports H1102 of the recording element base plate correspond to the ink supply ports H1201 of the first plate H1200, respectively, and then, the first recording element base plate H1100 and the second recording element base plate H1101 are positioned and bonded to the first plate H1200 to be fixed in good precision. Here, it is desirable to use the first bonding agent H1202 (see, e.g., Figs. 10A and 10C) which has low viscosity with low hardening temperature so that it can be hardened in a short period of time, while having a relatively high hardness after being hardened, as well as a good resistance to ink. Such first bonding agent H1202 is, for example, a thermal hardening bonding agent having an epoxy resin as its

main component, and the thickness of the bonded layer should preferably be 50 μm or less.

The electric wiring tape H1300 is for the application of electric signals to the first recording element base plate H1100 and the second recording element base plate H1101 in order to discharge ink, and comprises a plurality of opened parts for incorporating each of the recording element base plates; electrode terminals H1302 corresponding to the electrode units H1104 on the respective recording element base plates; and the electrode terminal units H1303 to effectuate the electrical connection with the electric contact base plate H2200 which is provided with the external signal input terminals positioned on the edge portion of the wiring tape to receive electric signals from the apparatus main body. The electrode terminals H1302 and the electrode terminals H1303 are connected by use of a continuous wiring pattern of copper foil.

The electric wiring tape H1300, the first recording element base plate H1100, and the second recording element base plate H1101 are connected electrically, respectively. The connecting method is, for example, such that the electrode units H1104 of the recording element base pate and the electrode terminals H1302 of the electric wiring tape H1300 are electrically coupled by means of thermo-ultrasonic pressurized welding.

The second plate H1400 is, for example, one-sheet plate member of 0.5 to 1.0 mm thickness, and formed by metallic material, such as ceramics of alumina (Al_2O_3), Al, SUS, or the like. Then, this plate is configured to be provided with opening portions larger, respectively, than the contour dimensons of the first recording element base plate H1100 and the second recording element base plate H1101 bonded and fixed to the first plate H1200, and this plate is also bonded to the first plate H1200, by use of the second bonding agent H1203, so that the electric wiring tape H1300 can be electrically connected with the first recording element base plate H1100 and the second recording element base plate H1101 on the plane, thus bonding and fixing the reverse side of the electric wiring tape H1300 by use of a third bonding agent (not shown).

The electrically connected portions of the first recording element base plate H1100, the second recording element base plate H1101, and the electric wiring tape H1300 are sealed by a first sealant H1307 and a second sealant H1308 in order to protect the electrically connected portions from erosion due to ink, and external shocks as well. The first sealant seals mainly the reverse side of the connected portion between the electrode terminals H1302 of the electric wiring tape and the electrode units H1104 of the recording element base plate, and the outer circumferential portion of the recording element base

plate. The second sealant seals the surface side of the aforesaid connected portion.

Further, the electric contact base board H2200, which is provided with the external signal input terminals to receive electric signals from the apparatus main body, is electrically connected with the edge portion of the electric wiring tape by means of thermally pressurized bonding using an anisotropic conductive film or the like.

Then, the electric wiring tape H1300 is folded on one side face of the first plate H1200 to be bonded to the side face of the first plate H1200 by use of the third bonding agent. The third bonding agent is, for example, a thermo-hardening bonding agent of 10 to 100 μm thickness with an epoxy resin as its main component, for example.

<1 - 2> Ink supply unit

The ink supply member H1500 is formed by means of resin molding, for example. For the resin material thereof, it is desirable to use a resin material in which a glass filler is mixed in 5 to 40% for enhancement of the form robustness.

As shown in Figs. 4 and 7, the ink supply member H1500 is one of the constituents to form the ink supply unit H1003 that conducts ink from the ink tanks H1900 to the recording element unit H1002, and the ink flow paths H1501 are formed when the flow path formation member H1600 is welded thereto by means of ultrasonic

welding. Also, to the joint H1520 that couples the recording head with the ink tanks H1900, the filter H1700 is bonded by means of welding in order to prevent external dust particles from entering. Further, in order to prevent ink evaporation from the joint H1520, a sealing rubber H1800 is provided therefor.

Also, the ink supply member H1500 serves in part to hold the freely detachable and attachable ink tanks H1900, and also, it is provided with the first hole H1503 which engages with the second nail H1910 of the ink tanks H1900.

Also, as shown in Fig. 4, there are provided an installation guide H1601 to guide the recording head cartridge H1000 to the position of the carriage installation on the main body of an ink jet recording apparatus; a coupling portion where the recording head cartridge is installed and fixed to the carriage by use of a head set lever; an abutting portion H1509 for positioning the carriage in a designated position of installation in the direction X (carriage scanning direction); an abutting portion H1510 in the direction Y (recording medium carrying direction); and an abutting portion H1511 in the direction Z (ink discharging direction). Also, it is arranged to provide the terminal fixing portion H1512 that positions and fixes the electric contact base plate H2200 of the recording element unit H1002. Then, with a plurality of ribs arranged for the terminal fixing

portion H1512 and the circumference thereof, the robustness is enhanced for the surface where the terminal fixing portion H1512 is provided.

<1 - 3> Coupling of the recording head unit and the ink supply unit

As shown in Fig. 3, the recording head H1001 is completed by bonding the recording element unit H1002 with the ink supply unit H1003, and further with the tank holder H2000. The bonding is executed as follows:

The ink supply port (ink supply port H1201 of the first plate H1200) of the recording element unit H1002 and the ink supply port (ink supply port H1602 of the liquid flow path formation member H1600) of the ink supply unit H1003 should be communicated without causing any ink leakage. To this end, each of them is fixed by use of screws H2400 to be fixed under pressure with the joint rubber H2300 between them. Here, at the same time, the recording element unit H1002 is positioned and fixed exactly to the standard positions of the ink supply unit in the direction X, direction Y, and direction Z.

Then, the electric contact base plate H1301 of the recording element unit H1002 is positioned and fixed to one side face of the ink supply member H1500 by use of the terminal positioning pins H1515 (two locations) and the terminal positioning holes H1309 (two locations). The fixing method is, for example, caulking and fixing the terminal coupling pins H1515 provided for the ink

supply member H1500, but any other fixing means may be usable. Fig. 8 shows the finished condition.

Further, the coupling hole and coupling portion of the ink supply member H1500 with the tank holder are fitted into and coupled with the tank holder H2000 to complete the recording head H1001. Fig. 9 shows the completion thereof.

<2> Recording head cartridge

Fig. 1 and Fig. 2 are views which illustrate the installation of the recording head H1001 and ink tanks H1901, H1902, H1903, and H1904 which constitute a recording head cartridge H1000. Inside the ink tanks H1901, H1902, H1903, and H1904, ink of each corresponding color is contained, respectively. Also, as shown in Fig. 7, inside each of the ink tanks, the ink supply port H1907 is formed to supply ink retained in the ink tank to the recording head H1001. For example, when the ink tank H1901 is installed on the recording head H1001, the ink supply port H1907 of the ink tank H1901 is in contact under pressure with the filter H1700 installed for the joint portion H1520 of the recording head H1001. Then, black ink in the ink tank H1901 is supplied to the first recording element base plate from the ink supply port H1907 through the first plate H1200 by way of the ink flow path H1501 of the recording head H1001.

Then, ink is supplied to the bubbling chamber where the electrothermal converting device H1103 and

the discharge port H1107 are arranged, and ink is discharged toward a recording sheet serving as a recording medium by the application of thermal energy generated by the electrothermal converting device H1103.

Next, the description will be made of the step of fixing the first recording element base plate H1100 to the first plate H1200, in the manufacturing process of a recording head structured as described above.

Figs. 10A to 10C, Figs. 11A and 11B, and Figs. 12A and 12B are cross-sectional views which illustrate the method for manufacturing the ink jet recording head in accordance with one embodiment of the present invention. In this respect, Fig. 10A to Fig. 12B represent the section of the first recording element base plate H1100, taken in the longitudinal direction of the discharge port array thereof.

In Fig. 10A to Fig. 12B, reference mark H101 designates the transfer pin that coats bonding agent H1202; H106, the vacuum adsorption finger that adsorbs and positions the recording element base plate; H110 and H111, the CCD cameras that recognize the position of the recording element base plate; and H112 and H113, ultraviolet irradiation nozzles.

In the step of fixing the first recording element base plate H1100 to the first plate H1200, the bonding agent H1202 is at first coated on the transfer surface of the transfer pin H101 as shown in Fig. 10A. Then,

in continuation, as shown in Fig. 10B, the transfer surface of the transfer pin H101 is put in contact with the first plate H1200. Then, as shown in Fig. 10C, when the transfer pin H101 is released from the first plate H1200, the bonding agent H1202 is coated on the bonding locations of the first plate H1200.

At this juncture, it is arranged that the bonding agent H1202 is transferred to a position on the first plate H1200 from which it can shift to extend outside the position where the first recording element base plate H1100 is in contact with the first plate H1200. The bonding agent is a dual type ultraviolet and thermal hardening bonding agent, that is, the bonding agent can be hardened by the irradiation of ultraviolet rays, and also, by application of heat. The bonding agent thus used has also excellent resistance to ink, and excellent transferability as well.

Next, as shown in Fig. 11A, the surface of the ink flow path wall H1106 that forms the discharge port H1107 of the first recording element base plate H1100 is held by the vacuum adsorption finger H106, and the alignment mark (not shown) of the first recording element base plate H1100 is optically recognized by the CCD cameras H110 and H111 to position it with the first plate H1200.

In continuation, as shown in Fig. 11B, the vacuum adsorption finger H106 thus positioned descends to enable the first recording element base plate H1100 to

abut upon the first plate H1200 and to compress them. Then, the bonding agent H1202 is forced out to the edge portions of the first recording element base plate H1100 in the longitudinal direction as shown in Fig. 11B. In Fig. 11B, it appears as if the bonding agent H1202 is forced out only to each outer side of the ink flow path, but actually, the bonding agent is also slightly forced out into the ink flow path (particularly into the ink supply port H1102 (see Figs. 5 and 6)) to be described later.

Then, as shown in Fig. 12A, the bonding agent H1202 forced out from the edge portions is hardened by the irradiation of ultraviolet rays from the ultraviolet irradiation nozzles H112 and H113, while keeping the first recording element base plate H1100 and the first plate H1200 compressed. Thus, the first recording element base plate H1100 is positioned and fixed on the first plate H1200.

Further, after the vacuum is released and the vacuum adsorption finger H106 is moved, ultraviolet rays are again irradiated by the ultraviolet irradiation nozzles H112 and H113 to the surface of the discharge ports H1107 as shown in Fig. 12B, thus hardening the bonding agent H1202 which is slightly forced out into the ink flow paths (particularly, into the ink supply port H1102 (see Figs. 5 and 6)) in order to prevent the bonding agent from flowing out to clog the ink flow paths and discharge ports. As regards the

irradiation of ultraviolet rays on the bonding agent that is slightly forced out in the ink flow paths, the detailed description will be made later in conjunction with Figs. 16A and 16B.

After the bonding process, this assembled part is further heated in order to harden the bonding agent H1202 yet to be hardened in the locations where the ultraviolet rays cannot reach.

As described above, the bonding agent is positively forced out from the bonding surface. Then, with the ultraviolet rays irradiated to such particular locations, the recording element base plate and the supporting member can be fixed tentatively. Thus, kept in the state of being positioned in high precision, the next hardening process is performed, leading to the enhancement of productivity and quality. Further, it becomes possible to irradiate ultraviolet rays to the bonding agent which is forced out into the flow paths to achieve firmer fixation of the recording element base plate, while preventing the bonding agent from flowing into the flow paths.

Fig. 13 is a perspective view which shows the first recording element base plate H1100 shown in the process of assembling represented in Fig. 11B.

As shown in Fig. 13, the bonding agent H1202 is forced out from the edge portions of the first recording element base plate H1100 in the longitudinal direction.

Fig. 14 is a perspective view which shows the second recording element base plate H1101 shown in the process of assembling represented in Fig. 11B.

The second recording element base plate H1101 is also positioned and fixed on the first plate H1200 in the same process as the process described above. The bonding agent H1202 is forced out form the edge portions of the second recording element base plate H1101 in the longitudinal direction.

In this respect, if the thickness of the bonding agent is less than 4 μm after hardening, there is a fear that a bonding defect may occur, and if the thickness of the bonding agent is more than 10 μm, the heat radiation is blocked from the recording element base plate to the first plate, and there is a fear that ink may not be discharged normally. Therefore, it is desirable to set the thickness of the bonding agent H1202 between the recording element base plates H1100 and H1101, and the first plate H1200, at a value within a range of approximately 4 μm to 10 μm.

(Second Embodiment)

Fig. 15 is a cross-sectional view which shows the recording element included in an ink jet recording head in accordance with a fourth embodiment of the present invention in a state where it is mounted on a supporting member.

The recording element base plate 1 is arranged on the supporting member 2 with the function to discharge

recording liquid by means of the electrothermal converting devices provided therefor. The recording element base plate 1 is bonded to the supporting member 2 by use of a bonding resin or the like. The supporting member 2 is formed of ceramic, such as alumina (Al_2O_3), and the recording element base plate 1 is formed of silicon (Si).

Also, for the discharge port plate 3 provided for the recording element base plate 1 on one surface thereof, a plurality of discharge ports 3a are open in two lines in positions respectively facing the discharge energy generating elements (electrothermal converting devices, for example) 4 which serve as recording elements. Then, the discharge port array is formed in two lines that make a pair. On the central part of the recording element base plate 1 on the reverse side, each of the recording liquid supply ports 5 is open in a length which is almost the same as the length of each discharge port array in the arrangement direction, penetrating the supporting member 2 in order to supply recording liquid from the recording liquid supply flow paths 2a to the discharge ports 3a.

For the present embodiment, the recording liquid supply system is structured to be arranged in high density, but the main considerations are given as follows:

(1) The recording liquid supply flow path 2a should have a width large enough to supply a sufficient

amount of recording liquid to the recording liquid supply port 5.

(2) The partition wall 2b of the supporting member 2 should not be allowed to propagate any unfavorable influence of vibration waves to the adjacent supply flow paths 2a when recording liquid is discharged.

(3) The required assembling precision should not become too high for the assembly of the recording element base plate 1 with the supporting member 2.

(4) Stepped portions, between liquid supply flow path 2a and recording liquid supply port 5, which may cause bubble pools to form in the recording head, should not exist in the finished product.

Consequently, each of the recording liquid supply paths 2a of the present embodiment has a width which is smaller than the opening width of the inlet portions of the respective recording liquid supply ports 5, and the thickness of each partition wall 2b that partitions adjacent recording supply flow paths 2a is made larger than the pitch between the inlet portions of the adjacent recording liquid supply ports 5. More specifically, the width A of the recording liquid supply path 2a of the present embodiment is set at 0.6 mm; the thickness B of the partition wall 26, 0.63mm; the pitch C between the inlet portions of the adjacent recording liquid supply ports 5, approximately 0.25 mm. Also, each of the supply ports 5 is formed in a tapered shape, reducing the flow path width in the

direction away from the liquid supply path 2a toward the outlet portion. Here, for the present embodiment, a five-liquid flow path system is exemplified, but the number of liquid flow paths for the system is not necessarily limited thereto.

In accordance with the present embodiment, the partition wall 2b is arranged to be thicker than the pitch between the inlet portions of the adjacent recording liquid flow paths 5 (that is, the width of the recording liquid supply flow path 2a of the supporting member 2 is smaller than the opening diameter of the recording liquid supply port 5 of the recording element base plate 1). Therefore, it becomes possible to suppress the propagation of vibration waves that may be carried to adjacent supply flow paths 2a through the partition walls 2b when recording liquid is discharged, thus enhancing the discharging performance of the recording liquid. Also, with the partition wall 2b arranged in a thickness larger than the pitch between adjacent recording liquid supply ports 5 themselves, there is no need for making the assembling precision high for the recording element base plate 1 with respect to the supporting member 2. In other words, this arrangement leads to the enhancement of productivity.

Figs. 16A and 16B are cross-sectional views which illustrate the steps of bonding the recording element

base plate and the supporting member represented in Fig. 15.

For the present embodiment, the bonding agent 10 of ultraviolet (UV) light hardening type is used for bonding the recording element base plate 1 and the supporting member 2. Then, with the bonding agent 10, the step that may be created between the recording element base plate 1 and the supporting member 2 is buried to prevent unwanted liquid pools, as well as bubble pools, from being generated in the recording liquid residing in each supply flow path. For the mode in which plural lines of recording liquid supply ports are provided for one recording element base plate as in the present embodiment, it becomes possible to achieve manufacture of the recording element base plate having the supply ports in high density by arranging the structure as the present invention, that is, to implement the manufacture of the recording element base plate at lower costs. Further, even at high density, it is possible to make the thickness of each wall between the supply flow paths of the supporting member 2 larger to a certain extent, hence preventing crosstalk, while contributing to the enhancement of productivity.

The bonding agent 10 coated on the bonding face between the recording element base plate 1 and the supporting member 2 is forced out between the upper face of the supporting member 2 and the side face of

the recording liquid supply port 5, respectively, as shown in Figs. 16A and 16B, when the recording element base plate 1 and the supporting member 2 are pressed to each other. Ultraviolet rays are irradiated from above the recording element base plate 1 to the bonding agent 10 thus forced out. Then, the bonding agent 10 is hardened, and consequently, the adjacent flow paths 2a themselves are sealed more reliably. Here, as shown in Fig. 16B, the discharge port plate 3 is formed by a transparent resin material or the like, thus making it possible to transmit ultraviolet rays. Also, the ultraviolet rays scatter, as shown in Fig. 16B, when transmitted through the discharge port plate 3, and further, being diffused when reflected from the surface of the recording liquid supply port 5 and recording liquid supply flow path 2a, the ultraviolet rays reach the bonding agent 10 which is forced out into the recording liquid supply port of the recording element base plate, thus quickly hardening the bonding agent thus forced out.

As a result, the recording element base plate 1 and the supporting member 2 can be tentatively fixed more firmly. Further, as described earlier, the stepped portions on the bonded face between the recording element base plate 1 and the supporting member 2 can be buried by use of the bonding agent, hence preventing unwanted liquid pools, as well as bubble pools, from being generated.

For the present embodiment, the width of the recording liquid supply flow path 2a is made smaller than the opening width of the inlet portion of the recording liquid supply port 5. There occur steps that may become liquid pools of recording liquid on each bonding portion between the supporting member 2 and the recording element base plate 1. However, as described above, each of these steps is buried with the forced-out bonding agent 10, and then, such bonding agent 10 can be hardened by the irradiation of ultraviolet rays from above the recording element base plate 1. Therefore, even if the structure is arranged to make the width of the recording liquid supply flow path 2a smaller than the opening width of the inlet portion of the recording liquid supply port 5, there is no possibility that liquid pools are formed in the recording liquid in the supply path. Thus, the liquid supply performance is not spoiled at all.

In this respect, the bonding agent 10 usable for the present embodiment is not necessarily limited to the type of ultraviolet hardening only. If the dual type ultraviolet and thermal hardening bonding agent 10 is used, the bonding agent 10 may be heated in addition to being irradiated by ultraviolet rays as described above, thus hardening the bonding agent 10 more reliably.

Now, the description has been made of the side shooter type of bubble jet method that uses

electrothermal converting devices for generating thermal energy as the recording method for each of the above embodiments. The present invention, however, is not limited to this type. It is of course applicable to the so-called piezo-discharge method that uses electro-mechanical converting devices, and the ink jet head of the edge shooter type, for example.